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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/993,208	11/16/2001	Jinbao Jiao	AP01979 8084 EXAMINER	
22917	7590 01/06/2004			
MOTOROLA, INC. 1303 EAST ALGONQUIN ROAD IL01/3RD			AFTERGUT, JEFF H	
			ART UNIT	PAPER NUMBER
SCHAUMBU	RG, IL 60196		1733	
			DATE MAILED: 01/06/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)
Advisory Action	09/993,208	JIAO ET AL.
Advisory Action	Examiner	Art Unit
	Jeff H. Aftergut	1733
The MAILING DATE of this communication appe	ars on the cover sheet with the c	correspondence address
THE REPLY FILED 08 December 2003 FAILS TO PLACE Therefore, further action by the applicant is required to available function under 37 CFR 1.113 may only be either: (1) condition for allowance; (2) a timely filed Notice of Appeal Examination (RCE) in compliance with 37 CFR 1.114.	oid abandonment of this applica a timely filed amendment which	ation. A proper reply to a
PERIOD FOR RE	PLY [check either a) or b)]	
a) The period for reply expiresmonths from the mailing b) The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire I ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS 706.07(f). Extensions of time may be obtained under 37 CFR 1.136(a). The fee have been filed is the date for purposes of determining the period of	Advisory Action, or (2) the date set forth ater than SIX MONTHS from the mailing FILED WITHIN TWO MONTHS OF THE date on which the petition under 37 CFI f extension and the corresponding amo	g date of the final rejection. HE FINAL REJECTION. See MPEP R 1.136(a) and the appropriate extension unt of the fee. The appropriate extension
ee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the 2) as set forth in (b) above, if checked. Any reply received by the Official imely filed, may reduce any earned patent term adjustment. See 37 C	ce later than three months after the mail FR 1.704(b).	ing date of the final rejection, even if
 A Notice of Appeal was filed on Appellant's 37 CFR 1.192(a), or any extension thereof (37 CFF 	R 1.191(d)), to avoid dismissal of	
2. The proposed amendment(s) will not be entered be	ecause:	
(a) they raise new issues that would require furthe	·	see NOTE below);
(b) they raise the issue of new matter (see Note b	•	
(c) ☐ they are not deemed to place the application ir issues for appeal; and/or	n better form for appeal by mate	rially reducing or simplifying the
(d) they present additional claims without cancelling	ng a corresponding number of fi	nally rejected claims.
NOTE: See Continuation Sheet.		
3. Applicant's reply has overcome the following reject		
 Newly proposed or amended claim(s) would canceling the non-allowable claim(s). 	be allowable if submitted in a se	parate, timely filed amendment
5.☐ The a)☐ affidavit, b)☐ exhibit, or c)☐ request for application in condition for allowance because:		dered but does NOT place the
 The affidavit or exhibit will NOT be considered becaraised by the Examiner in the final rejection. 	ause it is not directed SOLELY to	o issues which were newly
7. For purposes of Appeal, the proposed amendments explanation of how the new or amended claims we		
The status of the claim(s) is (or will be) as follows:		
Claim(s) allowed:		
Claim(s) objected to:		
Claim(s) rejected: <u>1-5,7,10-12,21-23 and 26-28</u> .		
Claim(s) withdrawn from consideration: 11, 12, 27,	<u>28</u> .	
8.☐ The drawing correction filed on is a)☐ appr	oved or b) disapproved by th	ne Examiner.
9. Note the attached Information Disclosure Statemen	it(s)(PTO-1449) Paper No(s)	•
0. Other:		
		Jet/H. Aftergut Primare Examiner

Continuation of 2. NOTE: The proposed amendment now requires the inclusion of a solder paste on the circuit board (applied via screening) as well as the placement of components onto the solder paste disposed on the board. It additionally requires that the heating t cure the adhesive also causes the reflowing of the solder paste to secure the components with the solder paste. Neither were previously considered and as such would require further search and/or consideration.